Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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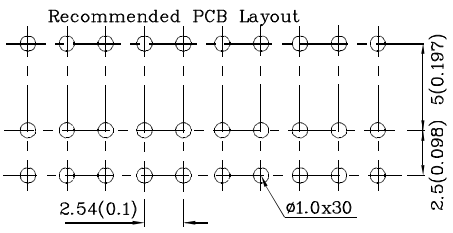
SunLED
www.SunLEDusa.com

Part Number: XGUGUYX10D

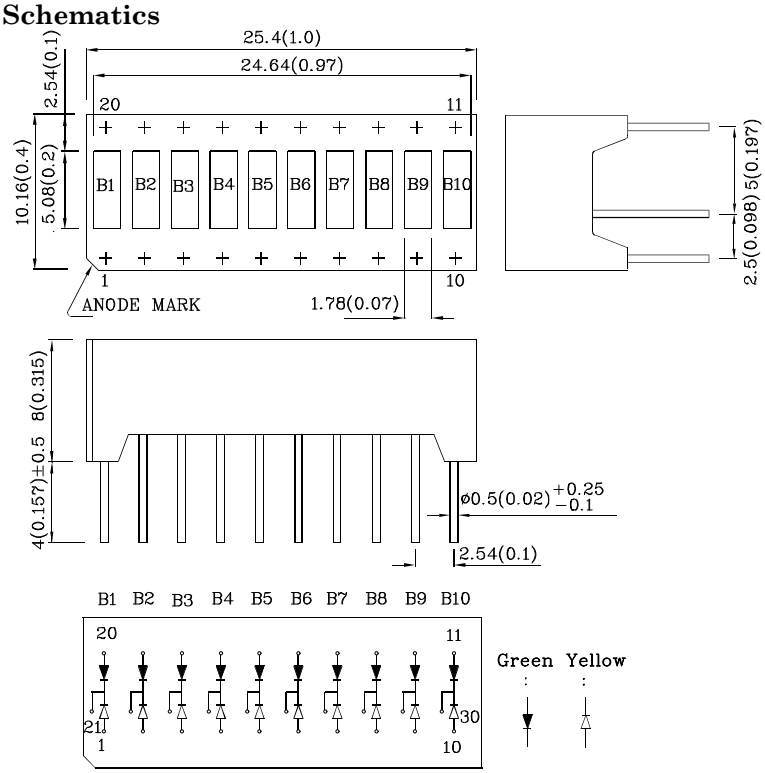
10 SEGMENT BAR GRAPH ARRAY

Features

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- Standard configuration: Gray face w/ white segments
- RoHS compliant



Package Schematics



Notes:
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A=25°C)		**Green (GaP)**	**Yellow (GaAsP/ GaP)**	**Unit**
Reverse Voltage	V_R	5	5	V
Forward Current	I_F	25	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	140	140	mA
Power Dissipation	P_D	62.5	75	mW
Operating Temperature	T_A	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3~5 Seconds			

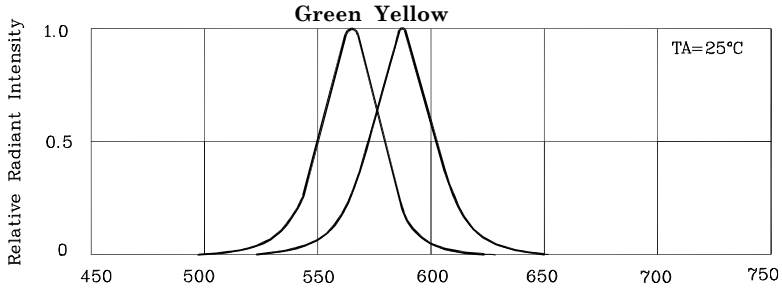
A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T_A=25°C)		**Green (GaP)**	**Yellow (GaAsP/ GaP)**	**Unit**
Forward Voltage (Typ.) (I_F=10mA)	V_F	2	1.95	V
Forward Voltage (Max.)(I_F=10mA)	V_F	2.5	2.5	V
Reverse Current (Max.) (V_R=5V)	I_R	10	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I_F=10mA)	λP	565*	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I_F=10mA)	λD	568*	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I_F=10mA)	△λ	30	35	nm
Capacitance (Typ.) (V_F=0V, f=1MHz)	C	15	20	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (IF=10mA) ucd min.	Luminous Intensity CIE127-2007* (IF=10mA) ucd typ.	Wavelength CIE127-2007* nm λP	Description
XGUGUYX10D	Green	GaP	5600 1400*	11990 3990*	565*	10 Segments Bar graph-Display
	Yellow	GaAsP/GaP	2200 900*	8990 2390*	590*	

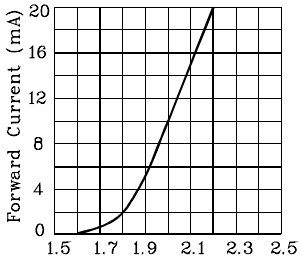
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Oct 18,2016 XDSA1919 V8-X Layout: Maggie L.

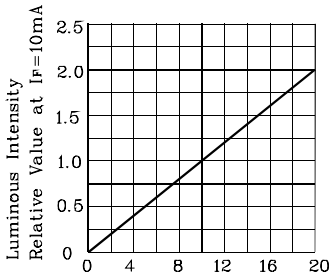


RELATIVE INTENSITY Vs. CIE WAVELENGTH

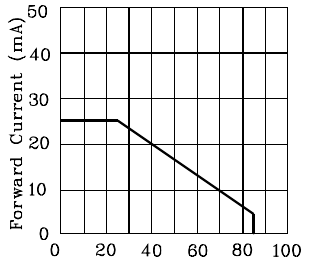
❖ Green



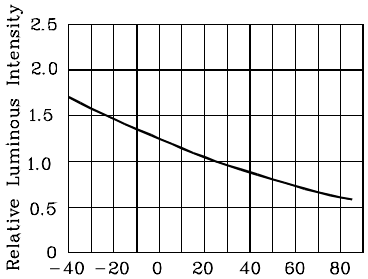
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

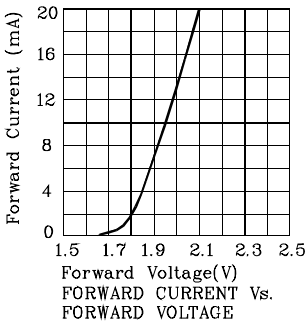


FORWARD CURRENT
DERATING CURVE

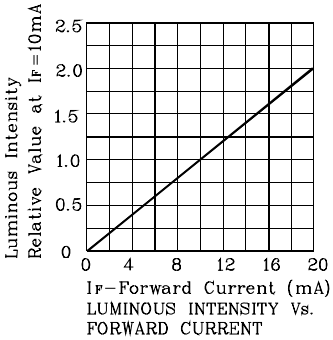


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

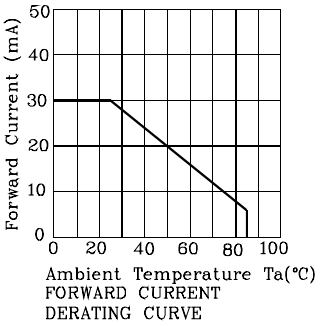
❖ Yellow



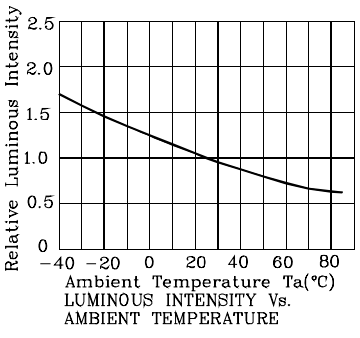
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

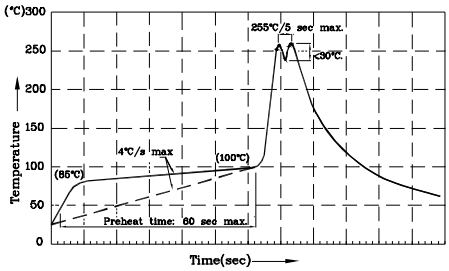


FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



Notes:
1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.
7. During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

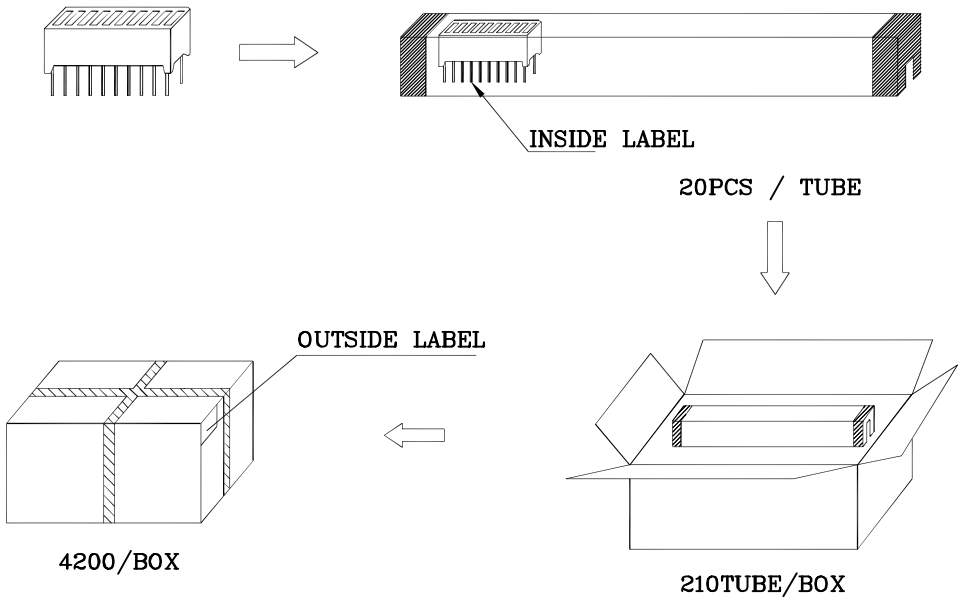
1. Wavelength: +/-1nm

2. Luminous Intensity / Luminous Flux: +/-15%

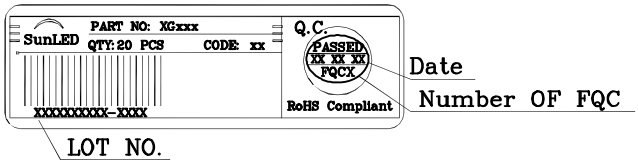
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

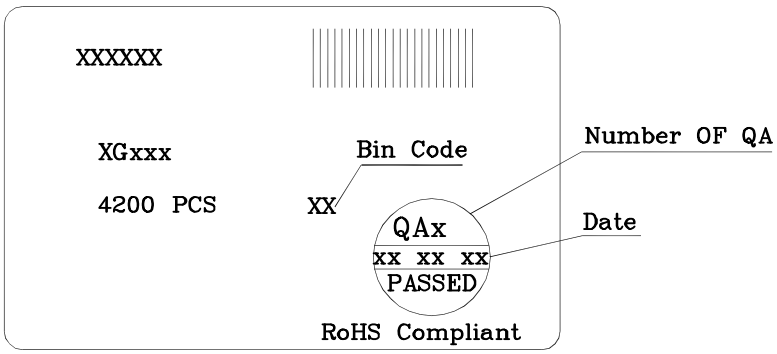
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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